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Global Wafer Grinding and Dicing Service Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

https://marketpublishers.com/r/G7EE04A47FD1EN.html
Date: January 2026
Pages: 153
Price: US$ 3,480.00 (Single User License)
ID: G7EE04A47FD1EN

Abstracts

According to our (Global Info Research) latest study, the global Wafer Grinding and Dicing Service market size was valued at US$ 654 million in 2025 and is forecast to a readjusted size of US$ 1191 million by 2032 with a CAGR of 9.0% during review period.

Wafer backgrinding, also known as Wafer thinning, is a semiconductor device fabrication step during which wafer thickness is reduced to allow for stacking and high density packaging of integrated circuits (IC).

Global key players of Wafer Grinding and Dicing Service include Micross Components, QP Technologies, Integra Technologies, Suzhou Baikejing Electronic Technology, YoungTek Electronics Corp., etc. The top five players hold a share about 26%. Asia-Pacific is the largest market, and has a share about 73%, followed by North America and Europe with share 17% and 8%, separately. In terms of product type, 300mm Wafer is the largest segment, occupied for a share of 78%. In terms of application, Logic Chip is the largest field with a share about 36 percent.

This report is a detailed and comprehensive analysis for global Wafer Grinding and Dicing Service market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Wafer Grinding and Dicing Service market size and forecasts, in consumption value ($ Million), sales quantity (K Pcs), and average selling prices (US$/Pc), 2021-2032

Global Wafer Grinding and Dicing Service market size and forecasts by region and country, in consumption value ($ Million), sales quantity (K Pcs), and average selling prices (US$/Pc), 2021-2032

Global Wafer Grinding and Dicing Service market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (K Pcs), and average selling prices (US$/Pc), 2021-2032

Global Wafer Grinding and Dicing Service market shares of main players, shipments in revenue ($ Million), sales quantity (K Pcs), and ASP (US$/Pc), 2021-2026

The Primary Objectives in This Report Are:
To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Wafer Grinding and Dicing Service
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global Wafer Grinding and Dicing Service market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Suzhou Baikejing Electronic Technology, Yima Semiconductor, Universen Hitec ltd, YoungTek Electronics Corp., Integrated Service Technology Inc (iST), Chnchip Integrated Circuit Co.,Ltd, Guangdong Leadyo IC Testing, King Long Technology, Shanghai Fine Chip Semiconductor, Jiangsu Nepes Semiconductor, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Wafer Grinding and Dicing Service market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

300mm Wafer

200mm Wafer

Others

Market segment by Application

Memory Chip

Logic Chip

Optical Sensor

MEMS

Others

Major players covered

Suzhou Baikejing Electronic Technology

Yima Semiconductor

Universen Hitec ltd

YoungTek Electronics Corp.

Integrated Service Technology Inc (iST)

Chnchip Integrated Circuit Co.,Ltd

Guangdong Leadyo IC Testing

King Long Technology

Shanghai Fine Chip Semiconductor

Jiangsu Nepes Semiconductor

Innotronix

Qipu Electronic Technology (Nantong) Co., Ltd

Micross Components

QP Technologies

Integra Technologies

MPE, Inc. (Micro Precision Engineering)

SVM (Silicon Valley Microelectronics)

GDSI (Grinding & Dicing Services Inc.)

Syagrus Systems

APD (American Precision Dicing, Inc)

Optim Wafer Services

NICHIWA KOGYO CO.,LTD.

High Components Aomori, Inc

FuRex

Intech Technologies International

Market segment by region, regional analysis covers
North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Wafer Grinding and Dicing Service product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Wafer Grinding and Dicing Service, with price, sales quantity, revenue, and global market share of Wafer Grinding and Dicing Service from 2021 to 2026.

Chapter 3, the Wafer Grinding and Dicing Service competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Wafer Grinding and Dicing Service breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026.and Wafer Grinding and Dicing Service market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Wafer Grinding and Dicing Service.

Chapter 14 and 15, to describe Wafer Grinding and Dicing Service sales channel, distributors, customers, research findings and conclusion.

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